VISCOM
vision technology

S6056BO

Ideally suited for double track operation and high throughput

Proven Viscom machine design for a wide range of applications

Perfect for large inspection objects

High-performance Viscom inspection software

Extremely high accuracy and inspection depth

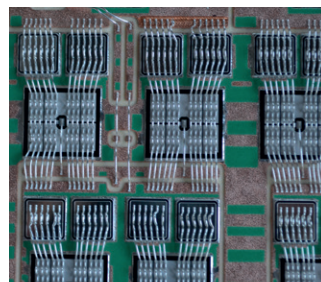
Bond

High-Performance Automatic Wire Bond Inspection

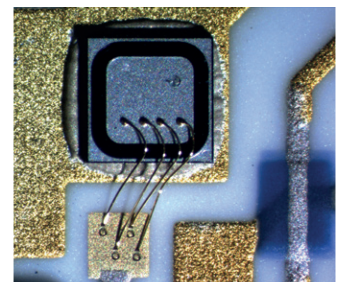
With the inspection system S6056BO, Viscom offers the best in-line technology and top performance for automatic optical inspection of wire bonds. Where high throughput is a must, double track operation can significantly cut inspection times. The system is particularly easy to customize beyond the standard features. Thus, even large inspection objects can be reliably and effectively inspected.

The high-precision inspection guarantees reliable defect detection of die, ball-wedge, wedge-wedge and security bonds. The inspection scope can be individually adapted for further applications beyond the range of standard defects. Damaged and misplaced components are also reliably detected. The high-performance Viscom inspection software takes on combined inspection of wire bonds and SMD assembly. With the high resolution, all bond sites and wires are detected. Wire path, dies and component position are only a part of the inspection scope. It makes no difference whether the connections are of copper, aluminum or gold, or whether ribbon or thick or thin wires are involved.

With a high-power Viscom SPC evaluation, numerous conclusions regarding the process can be made. As a result, defect causes are reduced to increase production quality. Remote diagnosis, worldwide maintenance and a Service hotline complete the offer.



Defect detection on multiwire connections and multiple loops



Bent wires

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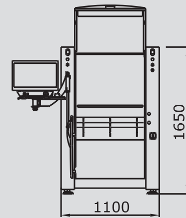
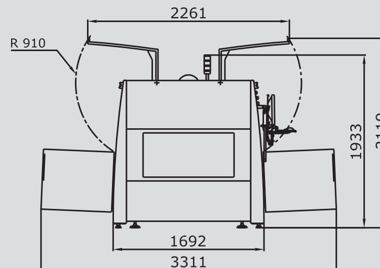
Technical Specifications

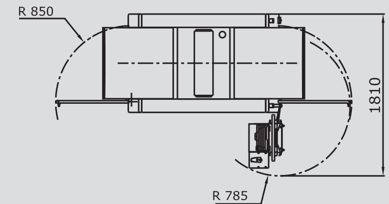
Front view



Side view



Top view



Dimensions in mm

		S6056BO STC	S6056BO DTC	S6056BO DSC
	Transport system	Single track	Double track	Dual shuttle
	Inspection concept	Single inspection		
Inspection scope	Bond	Ball bond, wedge bond, wire, die/SMD, ribbon		
Camera technology	**8M1 VHR module***			
	Number of modules per machine	1*		
	Number of cameras	1		
	Pixel size	5 µm/pixel or 2.5 µm/pixel*		
	8M1 SRW bond module*			
	Number of modules per machine	1*		
	Number of cameras	1		
	Pixel size	10 µm/pixel*		
	XM HR bond module*			
	Number of modules per machine	1*		
	Number of cameras	1		
	Pixel size	4.5 µm/pixel*		
Software	User interface	Viscom EasyPro		
	SPC	Viscom SPC (statistical process control), open interface (optional)		
	Verification station	Viscom HARAN		
	Remote diagnosis	Viscom SRC (software remote control) (optional)		
	Programming station	Viscom PST34 (optional)		
System computer	Operating system	Windows®		
	Processor	Intel® Core™ i7		
Substrate handling	Max. substrate size	300 mm x 400 mm (11.8" x 15.7") (L x W)*	290 mm x 200 mm (11.4" x 7.9") (L x W)*	
	Transport clearance	860 - 1180 mm ± 20 mm (33.9" - 46.5" ± 0.8")		
	Substrate clamping	Vacuum or mechanical clamping		
	Upper transport clearance	15 mm or 35 mm (0.6" or 1.4") (depending on camera technology*)		
Inspection speed		Up to 65 cm²/s, minimized handling time		
Other system data	Positioning/handling unit	Synchronous linear motors		
	Interfaces	SMEMA, SV70, customer-specific		
	Power requirements	400 V (other voltages on request), 3P/N/PE, 8 A, 4 - 6 bar working pressure		
	System dimensions	1100 mm x 1650 mm x 1692 mm (43.3" x 65" x 66.6") (W x H x D)		
	Weight	1700 kg (3748 lbs) (with transformer)		

*Standard configuration, other camera technologies, sizes, options, and boundary conditions on request.

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